Sensor Mechanical Engineer Intern (Stress Analysis)

Business Line Description

Sensors offers solutions that deliver trusted sensor information for secure, connected vehicles and the Internet of Things (IoT).

Job Summary:
As Sensors Stress Analysis Engineer you will assess the design of the MEMS-ASIC-Package System and work with Package and MEMS Designers and the Process Development Team to meet the design functionality.

Primary Responsibilities:

- Perform structural analysis to determine structural integrity using analysis tools, including hand calculations for preliminary sizing.
- Define tests, support their execution, analyze test results, and produce reports to validate and verify that the MEMS-ASIC-Package System and components meet the structural requirements and specifications.
- Investigate failures.
- Assist in the study of data and support the definition of structural design requirements.

Job Qualifications:

- Pursuit of Master of Science or PhD degree in Mechanical Engineering, or closely related field, with emphasis on solid, or structural, mechanics.
- Experience with industry standard Finite Element Analysis software such as Abaqus, and ANSYS. Familiarity with SolidWorks is a plus.
- Ability to develop structural models and analyses to verify structural integrity using mechanics and finite element analyses.
- Knowledge of structural dynamics, non-linear structure analysis, and fracture mechanics desired.
- Ideal candidate shall also have had coursework on Material Science and be familiar with MEMS or semiconductor fabrication processes.
- Familiarity with basic statistics, data mining and design of experiments.
- Must be able to collect, organize and analyze data; report findings, conclusions and recommendations.

To be considered for an internship with NXP, you must be returning to school (or graduating) at the end of the internship term. If you are graduating prior to June 2020, please apply for positions labeled “Graduate Hire” or “Entry Level”.